

APPENDIX: REDACTED PARAGRAPH

The redacted paragraph that began on page 1, at line 9 is as follows:

The present application is related to co-pending U.S. Patent Application Serial No. 09/731,997 [] (IBM Docket No. AUS9-2000-0415-US1) entitled "THERMOELECTRIC COOLERS WITH ENHANCED STRUCTURED INTERFACES" filed on December 7, 2000 [], to co-pending U.S. Patent Application S[s]erial No. 09/731,999 [] (IBM Docket No. AUS9-2000-0564-US1) entitled "COLD POINT DESIGN FOR EFFICIENT THERMOELECTRIC COOLERS" filed on December 7, 2000 [], and to co-pending U.S. Patent Application S[s]erial No. 09/731,614 [] (IBM Docket No. AUS9-2000-0556-US1) entitled "ENHANCED INTERFACE THERMOELECTRIC COOLERS USING ETCHED THERMOELECTRIC MATERIAL TIPS" filed on December 7, 2000 []. The content of the above mentioned commonly assigned, co-pending U. S. Patent applications are hereby incorporated herein by reference for all purposes.